

| L Number | Hits | Search Text | DB | Time stamp |
|----------|---------|--|---|------------------|
| 4 | 2657096 | wafer wafers substrate substrates semiconductor semiconductors | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2004/04/06 10:35 |
| 5 | 180482 | polish polishing planarize planarizing | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2004/04/06 10:35 |
| 6 | 1134973 | carrier carriers | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2004/04/06 10:36 |
| 7 | 87 | ((membrane membranes) with chambers with concentric) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2004/04/06 10:36 |
| 8 | 3 | (wafer wafers substrate substrates semiconductor semiconductors) same (polish polishing planarize planarizing) same (carrier carriers) same ((membrane membranes) with chambers with concentric) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2004/04/06 10:39 |
| 9 | 3 | (wafer wafers substrate substrates semiconductor semiconductors) same (carrier carriers) same ((membrane membranes) with chambers with concentric) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2004/04/06 10:44 |
| 12 | 22 | independently near3 controlable | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2004/04/06 10:45 |
| 13 | 0 | (carrier carriers) with ((membrane membranes) with chambers with concentric) with (independently near3 controlable) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2004/04/06 10:49 |
| 14 | 49 | "0115397" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2004/04/06 10:49 |
| 15 | 7972 | kajiwara.in. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2004/04/06 10:50 |
| 16 | 0 | "0115397" and kajiwara.in. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2004/04/06 10:50 |
| 17 | 19 | kajiwara.in. and subcarrier | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2004/04/06 11:21 |
| 18 | 30519 | retaining adj ring | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2004/04/06 11:21 |
| 19 | 1111692 | bearing bearings | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2004/04/06 11:21 |

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|----|-------|--|---|------------------|
| 20 | 3476 | ((retaining adj ring) with (bearing bearings)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/04/06 11:22 |
| 21 | 436 | ((retaining adj ring) with (bearing bearings)) and (carrier carriers) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/04/06 11:22 |
| 22 | 1 | | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/04/06 11:22 |
| 23 | 1932 | ((retaining adj ring) near5 (bearing bearings)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/04/06 11:28 |
| 24 | 247 | ((retaining adj ring) near5 (bearing bearings)) and (carrier carriers) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/04/06 11:23 |
| 25 | 31 | ((retaining adj ring) near5 (bearing bearings)) with (carrier carriers) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/04/06 11:23 |
| 26 | 108 | ((retaining adj ring) near5 (bearing bearings)) and (wafer wafers substrate substrates semiconductor semiconductors) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/04/06 12:04 |
| 27 | 2610 | hydrostatic adj bearing | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/04/06 12:04 |
| 28 | 2610 | (bearing bearings) and (hydrostatic adj bearing) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/04/06 12:05 |
| 29 | 82208 | (roller ball fluid) adj bearing | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/04/06 12:05 |
| 30 | 456 | (hydrostatic adj bearing). and ((roller ball fluid) adj bearing) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/04/06 12:05 |
| 31 | 27 | ((hydrostatic adj bearing) and ((roller ball fluid) adj bearing)) and (polish polishing planarize planarizing) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/04/06 12:05 |